

## PATENT ABSTRACTS OF JAPAN

(11)Publication number : 2002-271025

(43)Date of publication of application : 20.09.2002

(51)Int.Cl.

H05K 3/46

H01G 4/30

H01G 4/38

H01L 23/12

H05K 1/18

(21)Application number : 2001-070229

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(22)Date of filing : 13.03.2001

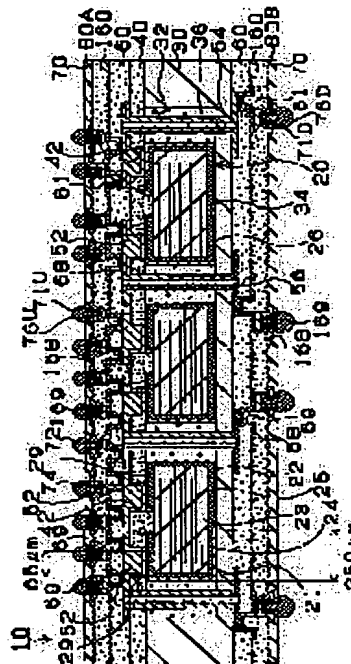
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## (54) PRINTED WIRING BOARD AND MANUFACTURING METHOD THEREFOR

## (57)Abstract:

**PROBLEM TO BE SOLVED:** To provide a printed wiring board which has a capacitor inside and has its connection reliability improved, and to provide a manufacturing method for the printed wiring board.

**SOLUTION:** On a chip capacitor 20 incorporated in a core substrate 30, a relatively large via hole 52 is formed, and in an inter-layer insulating layer 60 on the core substrate 30, via holes 69 connected to the via hole 52 are arranged. Consequently, terminals 21 and 22 of the chip capacitor 20 and the via hole 52 can securely be connected. Further, the surfaces of the metallized terminals 21 and 22 are coated with conductive paste 26, so the surfaces of the terminals 21 and 22 can be flat and the connectivity with the via hole 52 can be increased.



## LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's  
decision of rejection]

[Date of extinction of right]

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